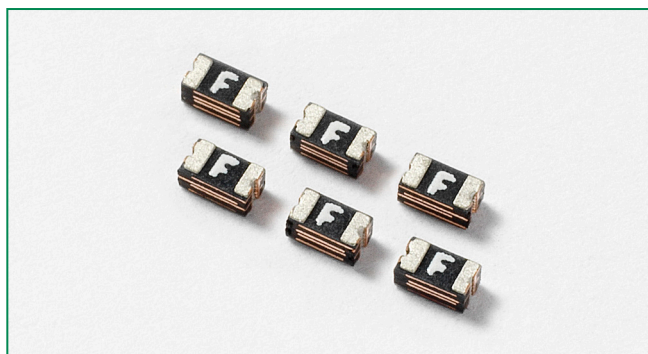




0603L Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E183209
	R50119118

Description

The 0603L Series PTC provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.



Features

- RoHS compliant, lead-free and halogen free
- Fast response to fault currents
- Compact design saves board space
- Low resistance
- Low-profile
- Compatible with high temperature solders

Applications

- USB peripherals
- Disk drives
- CD-ROMs
- Plug and play protection for motherboards and peripherals
- PDAs / digital cameras
- Game console port protection

Electrical Characteristics

Part Number	Marking	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	P_d typ. (W)	Maximum Time To Trip		Resistance		Agency Approvals	
							Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)		
0603L004	-	0.04	0.12	24	20	0.5	0.20	1.00	4.00	40.00	X	X
0603L010	C	0.10	0.30	15	40	0.5	0.50	1.00	0.900	6.000	X	X
0603L020	H	0.20	0.50	9	40	0.5	1.00	0.60	0.550	3.500	X	X
0603L025	I	0.25	0.55	9	40	0.5	8.00	0.08	0.500	3.000	X	X
0603L035	F	0.35	0.75	6	40	0.5	8.00	0.10	0.200	1.000	X	X
0603L050	J	0.50	1.00	6	40	0.5	8.00	0.10	0.100	0.680	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

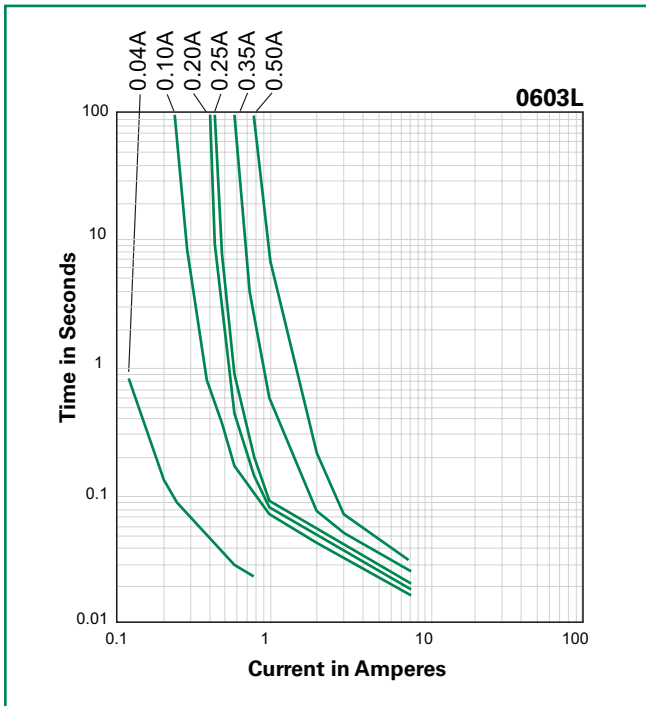
WARNING

- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage ($L di/dt$) above the rated voltage of the PPTC device.

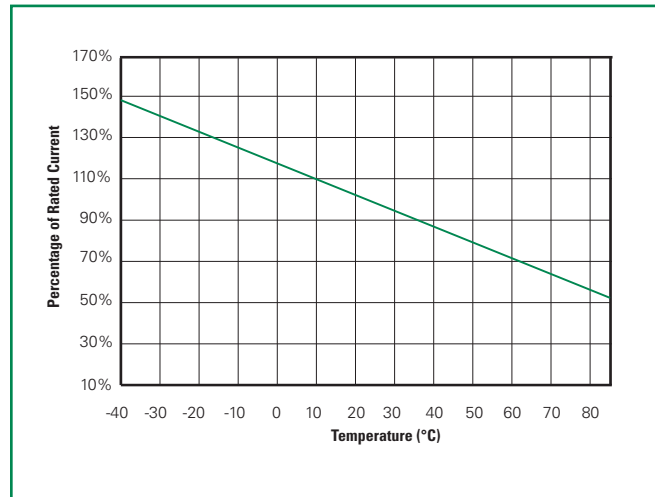
Temperature Rating

Ambient Operation Temperature									
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Part Number	Hold Current (A)								
0603L004	0.052	0.048	0.044	0.040	0.032	0.028	0.024	0.020	0.012
0603L010	0.13	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
0603L020	0.27	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
0603L025	0.32	0.29	0.27	0.25	0.21	0.18	0.16	0.14	0.10
0603L035	0.47	0.41	0.38	0.35	0.29	0.26	0.24	0.20	0.14
0603L050	0.67	0.59	0.54	0.50	0.41	0.37	0.34	0.29	0.20

Average Time Current Curves



Temperature Rating Curve

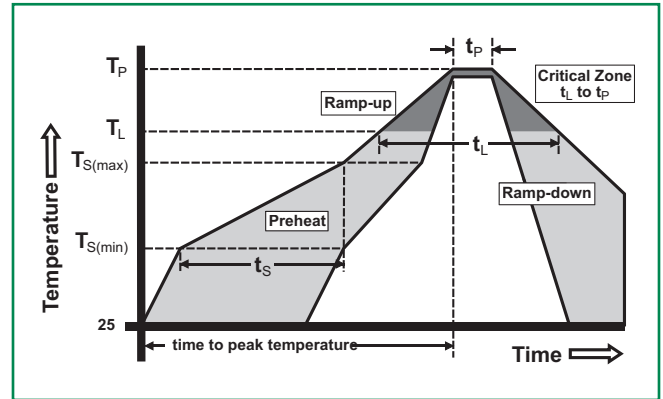


Note:
Typical Temperature derating curve, refer to table for derating data

The average time current curves and Temperature Rating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Soldering Parameters

Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{S(max)}$ to T_P)		3°C/second max
Pre Heat:	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (Min to Max) (t_s)	60 – 180 secs
Time Maintained Above:	Temperature (T_L)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak / Classification Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.



- All temperature refer to topside of the package, measured on the package body surface
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead
- Recommended maximum paste thickness is 0.25mm (0.010inch)
- Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

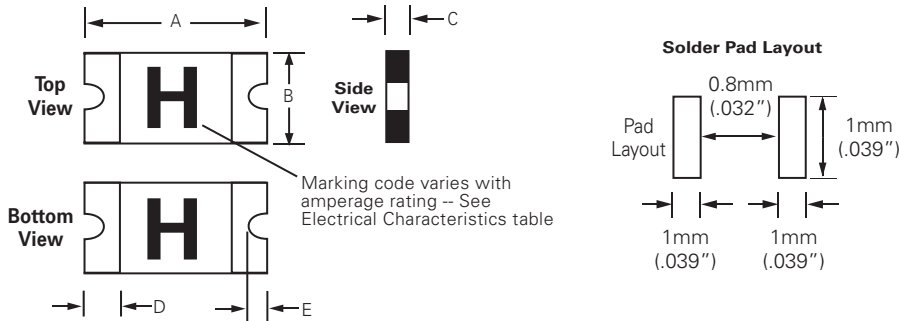
Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002, Category 3.

Environmental Specifications

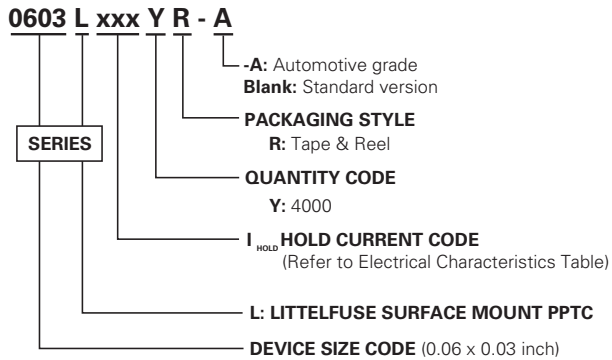
Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+10% typical resistance change
Humidity Aging	+85°C, 85% R.H., 100 hours -/+15% typical resistance change
Thermal Shock	MIL-STD-202, Method 107 +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883, Method 2007, Condition A No change
Moisture Sensitivity Level	Level 1, J-STD-020

Dimensions



Part Number	A				B				C				D				E			
	Inch		mm		Inch		mm		Inch		mm		Inch		mm		Inch		mm	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
0603L004	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L010	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L020	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L025	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.016	.030	0.40	0.75	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L035	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.030	.061	0.75	1.55	.006	.020	0.15	0.50	.004	.016	0.10	0.40
0603L050	.055	.071	1.40	1.80	.024	.039	0.60	1.00	.030	.061	0.75	1.55	.006	.020	0.15	0.50	.004	.016	0.10	0.40

Part Ordering Number System



Packaging

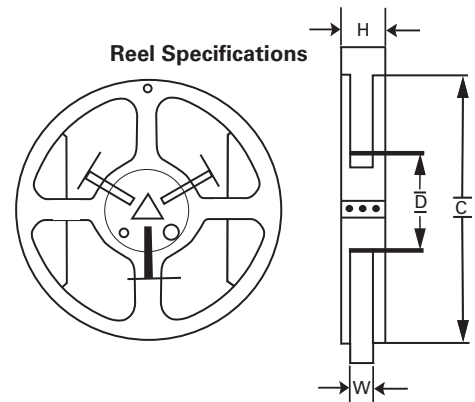
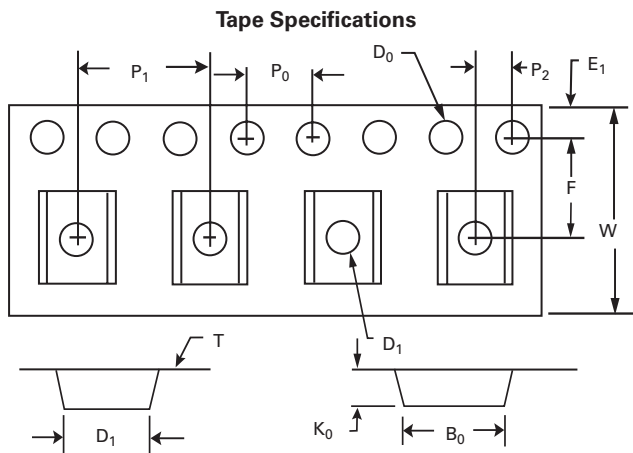
Part Number	Ordering Number	Halogen Free	I_{hold} (A)	I_{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
0603L004	0603L004YR	Yes	0.04	004	Tape and Reel	4000	YR
0603L010	0603L010YR	Yes	0.10	010	Tape and Reel	4000	YR
0603L020	0603L020YR	Yes	0.20	020	Tape and Reel	4000	YR
0603L025	0603L025YR	Yes	0.25	025	Tape and Reel	4000	YR
0603L035	0603L035YR	Yes	0.35	035	Tape and Reel	4000	YR
0603L050	0603L050YR	Yes	0.50	050	Tape and Reel	4000	YR

Tape and Reel Specifications

TAPE SPECIFICATIONS: EIA-481-1 (mm)		
	0603L004 0603L010 0603L020 0603L025	0603L035 0603L050
W	8.0+/- 0.30	8.0+/- 0.30
F	3.5+/- 0.05	3.5+/- 0.05
E₁	1.75+/- 0.10	1.75+/- 0.10
D₀	1.55+/- 0.05	1.55+/- 0.05
T	0.20+/- 0.10	0.20+/- 0.10
K₀	0.72+/- 0.10	0.96+/- 0.10
Leader min.	390	390
Trailer min.	160	160

REEL DIMENSIONS: EIA-481-1 (mm)	
C	Ø178+/-1.0
D	Ø60.2+/- 0.5
H	11.0+0.5
W	9.0+/- 1.5

Tape and Reel Diagram



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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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